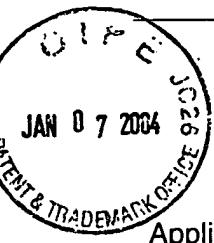


3732

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Densen Cao

Examiner: Ralph A. Lewis

Serial Number: 10/072,831

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For: "Curing Light"

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Response to Office Action

Mail Stop: NON-FEE AMENDMENT  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, Virginia 22313-1450

Honorable Commissioner:

This paper is intended to be fully responsive to the office action with a mailing date of 12/19/2003.

Amendment

*Subhik*  
Please cancel claims 1-17 without prejudice.

Please add the following new claims:

Claim 18 (newly presented) 18. A curing light comprising:

    a first semiconductor source of curing light,  
    a first primary heat sink to which said first semiconductor source of curing light is mounted,  
    a second semiconductor source of curing light,  
    a second primary heat sink to which said second semiconductor source of curing light is attached,  
    a secondary heat sink to which said first and second primary heat sinks are attached,  
    said first and second semiconductor sources of curing light being oriented so that light beams emanating from them overlap at least in part to provide an enhanced intensity light footprint which can be used to cure a desired material.

Claim 19 (newly presented) 19. A curing light as recited in claim 18 wherein said first and second primary heat sinks each have a mounting platform to which said semiconductor sources of curing light are attached.

Claim 20 (newly presented) 20. A curing light as recited in claim 19 wherein said mounting platforms are oriented to achieve said overlapping light beams.

Claim 21 (newly presented) 21. A curing light as recited in claim 18 further comprising:  
    a third semiconductor source of curing light,  
    a third primary heat sink to which said third semiconductor source of curing light is attached, and  
    said third primary heat sink being attached to said secondary heat sink.

Claim 22 (newly presented) 22. A curing light as recited in claim 21 wherein said third semiconductor source of curing light is oriented so that a light beam emanating from it overlaps said enhanced intensity light footprint at least in part

Claim 23 (newly presented) 23. A curing light as recited in claim 18 wherein said first semiconductor source of curing light emits light centered around a first wavelength  $\lambda_1$  and said second semiconductor source of curing light emits light centered around a second wavelength  $\lambda_2$ , and wherein  $\lambda_1$  is not equal to  $\lambda_2$ .

Claim 24 (newly presented) 24. A curing light as recited in claim 22  
wherein said first semiconductor source of curing light emits light centered around a first wavelength  $\lambda_1$ ;  
wherein said second semiconductor source of curing light emits light centered around a second wavelength  $\lambda_2$ ;  
wherein said third semiconductor source of curing light emits light centered around a third wavelength  $\lambda_3$ ; and  
wherein at least one of  $\lambda_1$  and  $\lambda_2$  is not equal to  $\lambda_3$ .

Claim 25 (newly presented) 25. A curing light comprising:  
a first semiconductor source of curing light,  
a second semiconductor source of curing light,  
a primary heat sink to which said first and second semiconductor sources of curing light are mounted,  
a secondary heat sink to which said primary heat sink is attached,  
said first and second semiconductor sources of curing light being oriented so that light beams emanating from them overlap at least in part to provide an enhanced intensity light footprint which can be used to cure a desired material.

Claim 26 (newly presented) 26. A curing light as recited in claim 25 wherein said primary

heat sink has a mounting platform to which said first and second semiconductor sources of curing light are attached.

Claim 27 (newly presented) 27. A curing light as recited in claim 26 wherein said mounting platform has surfaces are oriented to achieve said overlapping light beams via positioning of said semiconductor sources of curing light.

Claim 28 (newly presented) 28. A curing light as recited in claim 25 further comprising: a third semiconductor source of curing light.

Claim 29 (newly presented) 29 A curing light as recited in claim 28 wherein said third semiconductor source of curing light is oriented so that a light beam emanating from it overlaps said enhanced intensity light footprint at least in part

Claim 30 (newly presented) 30. A curing light as recited in claim 25 wherein said first semiconductor source of curing light emits light centered around a first wavelength  $\lambda_1$  and said second semiconductor source of curing light emits light centered around a second wavelength  $\lambda_2$ , and wherein  $\lambda_1$  is not equal to  $\lambda_2$ .

Claim 31 (newly presented) 31. A curing light as recited in claim 28 wherein said first semiconductor source of curing light emits light centered around a first wavelength  $\lambda_1$ ;

wherein said second semiconductor source of curing light emits light centered around a second wavelength  $\lambda_2$ ;

wherein said third semiconductor source of curing light emits light centered around a third wavelength  $\lambda_3$ ; and

wherein at least one of  $\lambda_1$  and  $\lambda_2$  is not equal to  $\lambda_3$ .